

| Dimensions |  |
| :---: | :---: |
| Chip Size | 0603 |
| L | $1.6 \mathrm{~mm}+/-0.15 \mathrm{~mm}$ |
| W | $0.8 \mathrm{~mm}+/-0.15 \mathrm{~mm}$ |
| T | $0.8 \mathrm{~mm}+/-0.07 \mathrm{~mm}$ |
| S | 0.7 mm MIN |
| B | $0.35 \mathrm{~mm}+/-0.15 \mathrm{~mm}$ |


| Packaging Specifications |  |
| ---: | :--- |
| Packaging: | T\&R, 180mm, Paper Tape |
| Packaging Quantity: | 4000 |


| General Information |  |
| ---: | :--- |
| Series: | SMD Comm C0G |
| Style: | SMD Chip |
| Description: | SMD, MLCC, Ultra-Stable, Low <br> Loss, Class I |
| Features: | Ultra-Stable, Low Loss, Class I |
| RoHS: | Yes |
| Termination: | Tin |
| Marking: | No |
| AEC-Q200: | No |
| Component Weight: | 3700 ug |
| Shelf Life: | 78 Weeks |
| MSL: | 1 |


| Specifications |  |
| :---: | :---: |
| Capacitance: | 30 pF |
| Measurement Condition: | 1 MHz 1.0 Vrms |
| Capacitance Tolerance: | 5\% |
| Voltage DC: | 100 VDC |
| Dielectric Withstanding Voltage: | 250 VDC |
| Temperature Range: | $-55 /+125^{\circ} \mathrm{C}$ |
| Temperature Coefficient: | COG |
| Capacitance Change with Reference to $+25^{\circ} \mathrm{C}$ and 0 VDC Applied (TCC): | $30 \mathrm{ppm} / \mathrm{C}, 1 \mathrm{MegaHz} 1.0 \mathrm{Vrms}$ |
| Dissipation Factor: | 0.1\% 1 MHz 1.0 Vrms |
| Aging Rate: | 0\% Loss/Decade Hour |
| Insulation Resistance: | 100 GOhms |

